



#15/16E
9/30/03

UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Chan, *et al.*

Serial No.: 09/757,364

Filed: January 8, 2001

For: Method for Joining Large Substrates

Examiner: John T. Harlan

Art Unit: 1733

Att'y Dkt.: 02EK-104742

**CERTIFICATE OF
MAILING/TRANSMISSION
(37 C.F.R. § 1.8A)**

I hereby certify that this correspondence is,
on the date shown below, being:
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9-17-03
Date

Jordan Wilson

DECLARATION OF ALBERT W. CHAN UNDER 37 C.F.R. §1.131

1. I, ALBERT W. CHAN, residing in San Jose, California, am one of the inventors of the invention of "Method for Joining Large Substrates," which was filed as U.S. Patent Serial Number 09/757,364 on January 8, 2001 (the '364 application).
2. Prior to September 21, 2000, my co-inventors and I had reduced the invention claimed in the '364 patent application to practice within the United States.
3. Attached hereto is an Exhibit of a copy of the original Invention Disclosure which formed the basis for the '364 application (the invention).
4. The dates contained in the original Invention Disclosure are blocked off, but all are prior to September 21, 2000.
5. The method claimed in the '354 application is recited in section IV.1 of the attached Invention Disclosure as having the purpose of joining large area substrates using a liquid polymer. The steps of the method are recited in section IV.2. of the attached Invention Disclosure as including dispensing liquid polymer at specified locations on a substrate, contacting an opposing substrate to contact the polymer, forcing the substrates together to squeeze the polymer over the surfaces, and curing the polymer.
6. As stated in section IV.6 and V.2 of the attached Invention Disclosure, the method was

applied to the joining of 6 inch by 6 inch substrates and laminate boards, and thus the invention worked for its intended purpose.

7. As described in Paragraphs 4 through 6, the attached Invention Disclosure establishes that the invention was reduced to practice and worked for its intended purpose prior to prior to September 21, 2000.

8. We have attempted to locate additional corroborating evidence in the form of pertinent documents, specifically pages of laboratory notebooks documenting the conception of invention, laboratory records, and monthly reports documenting the reduction to practice of the invention. However, these pertinent documents are not reasonably obtainable despite repeated attempts to locate them. The reason the records are difficult to locate is that the company at which I was employed at the time the invention was reduced to practice, Fujitsu Computer Packaging Technologies, Inc., was dissolved on or about October 2000. Some of the pertinent documents were destroyed, and the remaining were dispersed between Fujitsu Limited, Fujitsu America, Inc. (FAI) and Fujitsu Laboratories of America (FLA). I have contacted representatives at all three companies in an attempt to obtain these documents. However, my contacts, as of the date of this declaration, have not been able to locate any of these materials.

9. I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

September 15, 2003

Albert W. Chan

Albert W. Chan